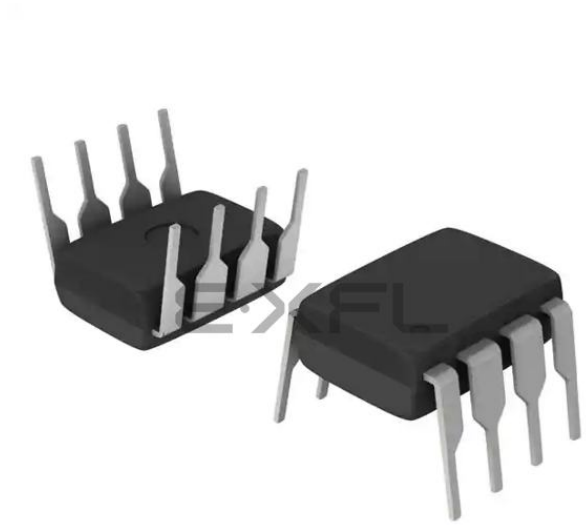


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	768B (512 x 12)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12f508-e-p

PIC12F508/509/16F505

8/14-Pin, 8-Bit Flash Microcontrollers

Devices Included In This Data Sheet:

- PIC12F508
- PIC12F509
- PIC16F505

High-Performance RISC CPU:

- Only 33 Single-Word Instructions to Learn
- All Single-Cycle Instructions Except for Program Branches, which are Two-Cycle
- 12-Bit Wide Instructions
- 2-Level Deep Hardware Stack
- Direct, Indirect and Relative Addressing modes for Data and Instructions
- 8-Bit Wide Data Path
- 8 Special Function Hardware Registers
- Operating Speed:
  - DC – 20 MHz clock input (PIC16F505 only)
  - DC – 200 ns instruction cycle (PIC16F505 only)
  - DC – 4 MHz clock input
  - DC – 1000 ns instruction cycle

Special Microcontroller Features:

- 4 MHz Precision Internal Oscillator:
  - Factory calibrated to ±1%
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Debugging (ICD) Support
- Power-On Reset (POR)
- Device Reset Timer (DRT)
- Watchdog Timer (WDT) with Dedicated On-Chip RC Oscillator for Reliable Operation
- Programmable Code Protection
- Multiplexed $\overline{\text{MCLR}}$ Input Pin
- Internal Weak Pull-Ups on I/O Pins
- Power-Saving Sleep mode
- Wake-Wp from Sleep on Pin Change
- Selectable Oscillator Options:
  - INTRC: 4 MHz precision Internal oscillator
  - EXTRC: External low-cost RC oscillator
  - XT: Standard crystal/resonator
  - HS: High-speed crystal/resonator (PIC16F505 only)
  - LP: Power-saving, low-frequency crystal
  - EC: High-speed external clock input (PIC16F505 only)

Low-Power Features/CMOS Technology:

- Operating Current:
  - < 175 µA @ 2V, 4 MHz, typical
- Standby Current:
  - 100 nA @ 2V, typical
- Low-Power, High-Speed Flash Technology:
  - 100,000 Flash endurance
  - > 40 year retention
- Fully Static Design
- Wide Operating Voltage Range: 2.0V to 5.5V
- Wide Temperature Range:
  - Industrial: -40°C to +85°C
  - Extended: -40°C to +125°C

Peripheral Features (PIC12F508/509):

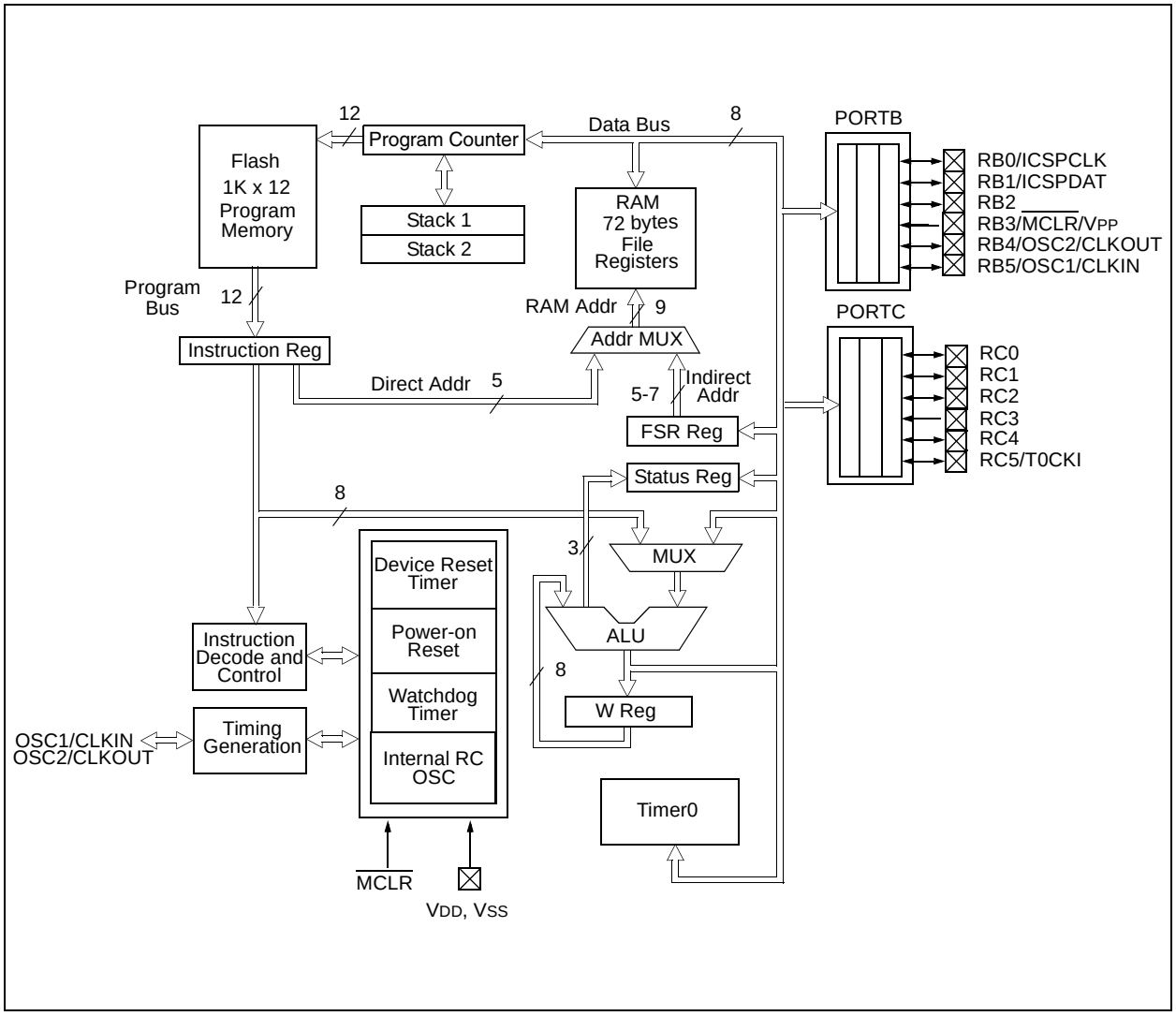
- 6 I/O Pins:
  - 5 I/O pins with individual direction control
  - 1 input only pin
  - High current sink/source for direct LED drive
  - Wake-on-change
  - Weak pull-ups
- 8-Bit Real-Time Clock/Counter (TMR0) with 8-Bit Programmable Prescaler

Peripheral Features (PIC16F505):

- 12 I/O Pins:
  - 11 I/O pins with individual direction control
  - 1 input only pin
  - High current sink/source for direct LED drive
  - Wake-on-change
  - Weak pull-ups
- 8-Bit Real-Time Clock/Counter (TMR0) with 8-Bit Programmable Prescaler

NOTES:

FIGURE 3-2: PIC16F505 BLOCK DIAGRAM



4.0 MEMORY ORGANIZATION

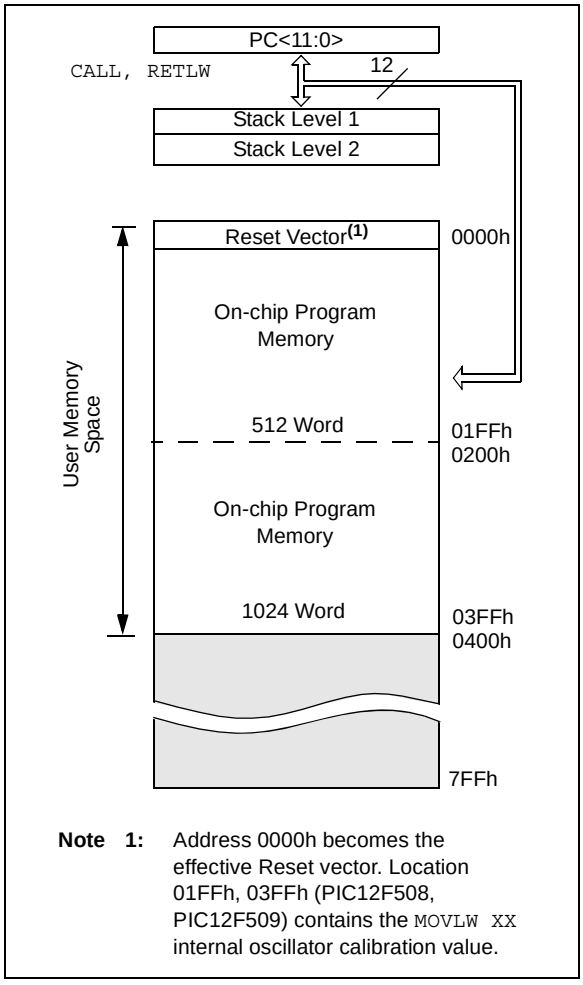
The PIC12F508/509/16F505 memories are organized into program memory and data memory. For devices with more than 512 bytes of program memory, a paging scheme is used. Program memory pages are accessed using one STATUS register bit. For the PIC12F509 and PIC16F505, with data memory register files of more than 32 registers, a banking scheme is used. Data memory banks are accessed using the File Select Register (FSR).

4.1 Program Memory Organization for the PIC12F508/509

The PIC12F508 device has a 10-bit Program Counter (PC) and PIC12F509 has a 11-bit Program Counter (PC) capable of addressing a 2K x 12 program memory space.

Only the first 512 x 12 (0000h-01FFh) for the PIC12F508, and 1K x 12 (0000h-03FFh) for the PIC12F509 are physically implemented (see Figure 4-1). Accessing a location above these boundaries will cause a wrap-around within the first 512 x 12 space (PIC12F508) or 1K x 12 space (PIC12F509). The effective Reset vector is a 0000h (see Figure 4-1). Location 01FFh (PIC12F508) and location 03FFh (PIC12F509) contain the internal clock oscillator calibration value. This value should never be overwritten.

FIGURE 4-1: PROGRAM MEMORY MAP AND STACK FOR THE PIC12F508/509



Note 1: Address 0000h becomes the effective Reset vector. Location 01FFh, 03FFh (PIC12F508, PIC12F509) contains the `MOVLW XX` internal oscillator calibration value.

4.4 STATUS Register

This register contains the arithmetic status of the ALU, the Reset status and the page preselect bit.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS,` will clear the upper three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where `u` = unchanged).

Therefore, it is recommended that only `BCF`, `BSF` and `MOVWF` instructions be used to alter the STATUS register. These instructions do not affect the Z, DC or C bits from the STATUS register. For other instructions which do affect Status bits, see **Section 8.0 "Instruction Set Summary"**.

REGISTER 4-1: STATUS REGISTER (ADDRESS: 03h) (PIC12F508/509)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
GPWUF	—	PA0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **GPWUF:** GPIO Reset bit
`1` = Reset due to wake-up from Sleep on pin change
`0` = After power-up or other Reset

bit 6 **Reserved**: Do not use

bit 5 **PA0**: Program Page Preselect bits(1)
`1` = Page 1 (200h-3FFh)
`0` = Page 0 (000h-1FFh)
Each page is 512 bytes.
Using the PA0 bit as a general purpose read/write bit in devices which do not use it for program page preselect is not recommended, since this may affect upward compatibility with future products.

bit 4 **$\overline{TO}$**: Time-Out bit
`1` = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
`0` = A WDT time-out occurred

bit 3 **$\overline{PD}$**: Power-Down bit
`1` = After power-up or by the `CLRWDT` instruction
`0` = By execution of the `SLEEP` instruction

bit 2 **Z**: Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1 **DC**: Digit Carry/$\overline{\text{Borrow}}$ bit (for `ADDWF` and `SUBWF` instructions)
`ADDWF:`
`1` = A carry from the 4th low-order bit of the result occurred
`0` = A carry from the 4th low-order bit of the result did not occur
`SUBWF:`
`1` = A borrow from the 4th low-order bit of the result did not occur
`0` = A borrow from the 4th low-order bit of the result occurred

bit 0 **C**: Carry/$\overline{\text{Borrow}}$ bit (for `ADDWF`, `SUBWF` and `RRF`, `RLF` instructions)

`ADDWF:`	`SUBWF:`	`RRF` or `RLF:`
`1` = A carry occurred	`1` = A borrow did not occur	Load bit with LSb or MSb, respectively
`0` = A carry did not occur	`0` = A borrow occurred	

Note 1: This bit is used on the PIC12F509. For code compatibility do not use this bit on the PIC12F508.

REGISTER 4-2: STATUS REGISTER (ADDRESS: 03h) (PIC16F505)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
RBWUF	—	PA0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **RBWUF:** PORTB Reset bit
1 = Reset due to wake-up from Sleep on pin change
0 = After power-up or other Reset

bit 6 **Reserved**: Do not use

bit 5 **PA0**: Program Page Preselect bits
1 = Page 1 (200h-3FFh)
0 = Page 0 (000h-1FFh)
Each page is 512 bytes.
Using the PA0 bit as a general purpose read/write bit in devices which do not use it for program page preselect is not recommended, since this may affect upward compatibility with future products.

bit 4 **$\overline{TO}$**: Time-Out bit
1 = After power-up, CLRWDT instruction, or SLEEP instruction
0 = A WDT time-out occurred

bit 3 **$\overline{PD}$**: Power-Down bit
1 = After power-up or by the CLRWDT instruction
0 = By execution of the SLEEP instruction

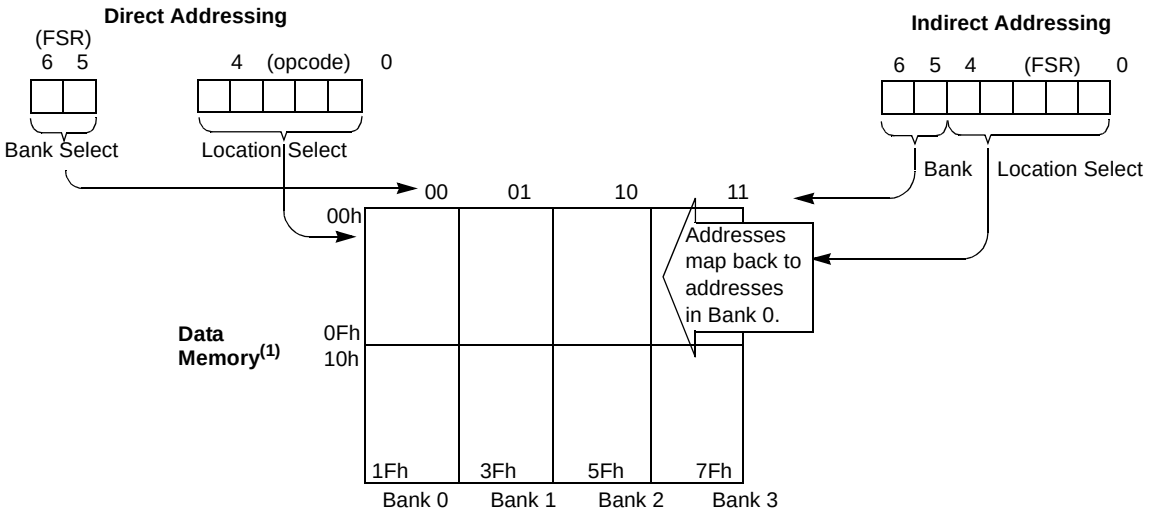
bit 2 **Z**: Zero bit
1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC**: Digit Carry/$\overline{Borrow}$ bit (for ADDWF and SUBWF instructions)
ADDWF:
1 = A carry from the 4th low-order bit of the result occurred
0 = A carry from the 4th low-order bit of the result did not occur
SUBWF:
1 = A borrow from the 4th low-order bit of the result did not occur
0 = A borrow from the 4th low-order bit of the result occurred

bit 0 **C**: Carry/$\overline{Borrow}$ bit (for ADDWF, SUBWF and RRF, RLF instructions)

ADDWF:	SUBWF:	RRF or RLF:
1 = A carry occurred	1 = A borrow did not occur	Load bit with LSb or MSb, respectively
0 = A carry did not occur	0 = A borrow occurred	

FIGURE 4-8: DIRECT/INDIRECT ADDRESSING (PIC16F505)



Note 1: For register map detail, see **Section 4.3 "Data Memory Organization"**.

5.5 I/O Programming Considerations

5.5.1 BIDIRECTIONAL I/O PORTS

Some instructions operate internally as read followed by write operations. The BCF and BSF instructions, for example, read the entire port into the CPU, execute the bit operation and re-write the result. Caution must be used when these instructions are applied to a port where one or more pins are used as input/outputs. For example, a BSF operation on bit 5 of PORTB/GPIO will cause all eight bits of PORTB/GPIO to be read into the CPU, bit 5 to be set and the PORTB/GPIO value to be written to the output latches. If another bit of PORTB/GPIO is used as a bidirectional I/O pin (say bit 0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the Input mode, no problem occurs. However, if bit 0 is switched into Output mode later on, the content of the data latch may now be unknown.

Example 5-1 shows the effect of two sequential Read-Modify-Write instructions (e.g., BCF, BSF, etc.) on an I/O port.

A pin actively outputting a high or a low should not be driven from external devices at the same time in order to change the level on this pin ("wired OR", "wired AND"). The resulting high output currents may damage the chip.

EXAMPLE 5-1: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT(e.g., PIC16F505)

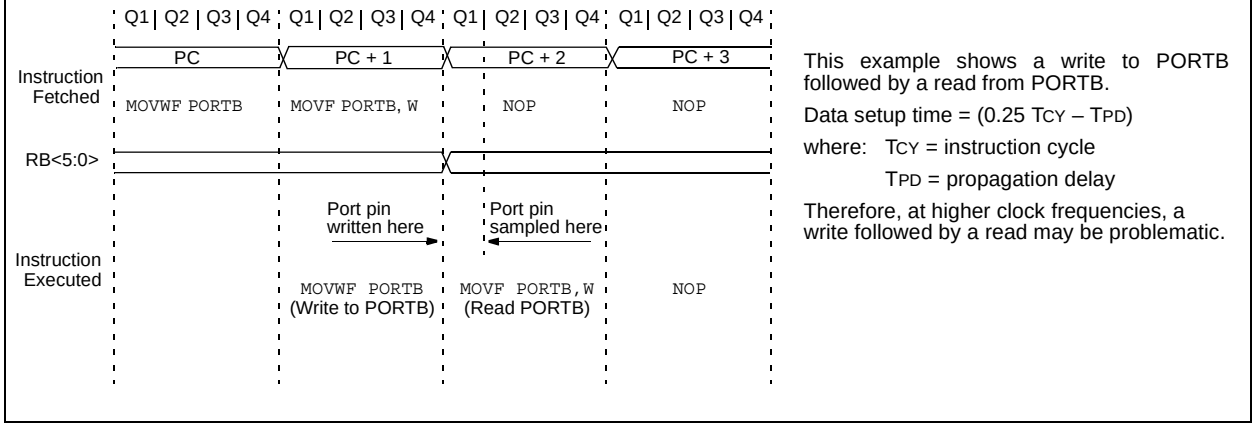
```
;Initial PORTB Settings
;PORTB<5:3> Inputs
;PORTB<2:0> Outputs
;
;                  PORTB latch  PORTB pins
;                  ----------   ----------
  BCF    PORTB, 5 ;--01 -ppp    --11 pppp
  BCF    PORTB, 4 ;--10 -ppp    --11 pppp
  MOVLW  007h;
  TRIS   PORTB    ;--10 -ppp    --11 pppp
;
```

Note 1: The user may have expected the pin values to be '--00 pppp'. The 2nd BCF caused RB5 to be latched as the pin value (High).

5.5.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-2). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction causes that file to be read into the CPU. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.

FIGURE 5-2: SUCCESSIVE I/O OPERATION (PIC16F505 Shown)



This example shows a write to PORTB followed by a read from PORTB.

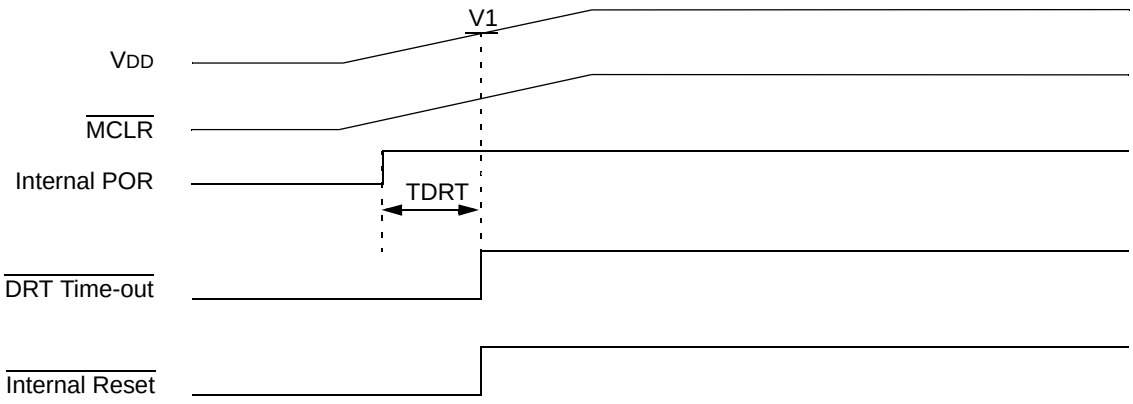
Data setup time = (0.25 T_{CY} – T_{PD})

where: T_{CY} = instruction cycle

T_{PD} = propagation delay

Therefore, at higher clock frequencies, a write followed by a read may be problematic.

FIGURE 7-10: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ TIED TO V_{DD}): SLOW V_{DD} RISE TIME



Note: When V_{DD} rises slowly, the T_{DRT} time-out expires long before V_{DD} has reached its final value. In this example, the chip will reset properly if, and only if, V1 ≥ V_{DD} min.

7.5 Device Reset Timer (DRT)

On the PIC12F508/509/16F505 devices, the DRT runs any time the device is powered up. DRT runs from Reset and varies based on oscillator selection and Reset type (see Table 7-6).

The DRT operates on an internal RC oscillator. The processor is kept in Reset as long as the DRT is active. The DRT delay allows VDD to rise above VDD min. and for the oscillator to stabilize.

Oscillator circuits based on crystals or ceramic resonators require a certain time after power-up to establish a stable oscillation. The on-chip DRT keeps the devices in a Reset condition for approximately 18 ms after MCLR has reached a logic high (VIH MCLR) level. Programming (GP3/RB3)/MCLR/VPP as MCLR and using an external RC network connected to the MCLR input is not required in most cases. This allows savings in cost-sensitive and/or space restricted applications, as well as allowing the use of the (GP3/RB3)/MCLR/VPP pin as a general purpose input.

The Device Reset Time delays will vary from chip-to-chip due to VDD, temperature and process variation. See AC parameters for details.

The DRT will also be triggered upon a Watchdog Timer time-out from Sleep. This is particularly important for applications using the WDT to wake from Sleep mode automatically.

Reset sources are POR, MCLR, WDT time-out and wake-up on pin change. See **Section 7.9.2 "Wake-up from Sleep", Notes 1, 2** and **3**.

7.6 Watchdog Timer (WDT)

The Watchdog Timer (WDT) is a free running on-chip RC oscillator, which does not require any external components. This RC oscillator is separate from the external RC oscillator of the (GP5/RB5)/OSC1/CLKIN pin and the internal 4 MHz oscillator. This means that the WDT will run even if the main processor clock has been stopped, for example, by execution of a SLEEP instruction. During normal operation or Sleep, a WDT Reset or wake-up Reset, generates a device Reset.

The TO bit (STATUS<4>) will be cleared upon a Watchdog Timer Reset.

The WDT can be permanently disabled by programming the configuration WDTE as a '0' (see **Section 7.1 "Configuration Bits"**). Refer to the PIC12F508/509/16F505 Programming Specifications to determine how to access the Configuration Word.

TABLE 7-6: DRT (DEVICE RESET TIMER PERIOD)

Oscillator Configuration	POR Reset	Subsequent Resets
INTOSC, EXTRC	18 ms (typical)	10 µs (typical)
HS(1), XT, LP	18 ms (typical)	18 ms (typical)
EC(1)	18 ms (typical)	10 µs (typical)

Note 1: PIC16F505 only.

7.6.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). If a longer time-out period is desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT (under software control) by writing to the OPTION register. Thus, a time-out period of a nominal 2.3 seconds can be realized. These periods vary with temperature, VDD and part-to-part process variations (see DC specs).

Under worst case conditions (VDD = Min., Temperature = Max., max. WDT prescaler), it may take several seconds before a WDT time-out occurs.

7.6.2 WDT PROGRAMMING CONSIDERATIONS

The CLRWDT instruction clears the WDT and the postscaler, if assigned to the WDT, and prevents it from timing out and generating a device Reset.

The SLEEP instruction resets the WDT and the postscaler, if assigned to the WDT. This gives the maximum Sleep time before a WDT wake-up Reset.

7.7 Time-out Sequence, Power-down and Wake-up from Sleep Status Bits (TO, PD, GPWUF/RBWUF)

The $\overline{TO}$, $\overline{PD}$ and (GPWUF/RBWUF) bits in the STATUS register can be tested to determine if a Reset condition has been caused by a Power-up condition, a $\overline{MCLR}$ or Watchdog Timer (WDT) Reset.

TABLE 7-8: $\overline{TO}$/$\overline{PD}$/(GPWUF/RBWUF) STATUS AFTER RESET

GPWUF/ RBWUF	$\overline{TO}$	$\overline{PD}$	Reset Caused By
0	0	0	WDT wake-up from Sleep
0	0	u	WDT time-out (not from Sleep)
0	1	0	$\overline{MCLR}$ wake-up from Sleep
0	1	1	Power-up
0	u	u	$\overline{MCLR}$ not during Sleep
1	1	0	Wake-up from Sleep on pin change

Legend: u = unchanged

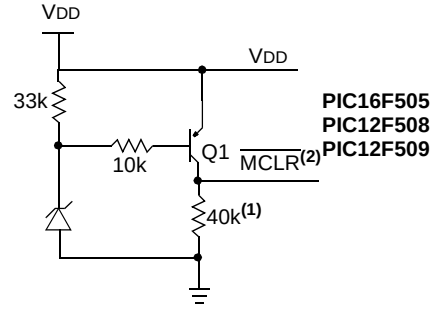
Note 1: The $\overline{TO}$, $\overline{PD}$ and GPWUF/RBWUF bits maintain their status (u) until a Reset occurs. A low-pulse on the $\overline{MCLR}$ input does not change the $\overline{TO}$, $\overline{PD}$ and GPWUF/RBWUF Status bits.

7.8 Reset on Brown-out

A brown-out is a condition where device power (V_{DD}) dips below its minimum value, but not to zero, and then recovers. The device should be reset in the event of a brown-out.

To reset PIC12F508/509/16F505 devices when a brown-out occurs, external brown-out protection circuits may be built, as shown in Figure 7-12 and Figure 7-13.

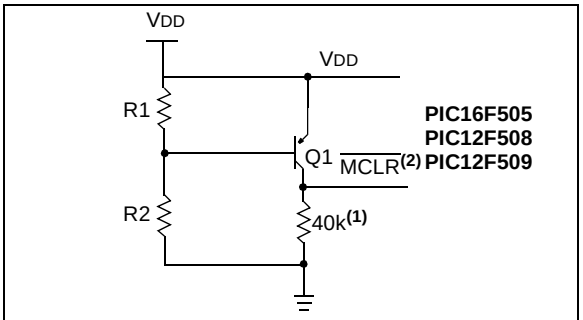
FIGURE 7-12: BROWN-OUT PROTECTION CIRCUIT 1



Note 1: This circuit will activate Reset when V_{DD} goes below Vz + 0.7V (where Vz = Zener voltage).

2: Pin must be confirmed as $\overline{MCLR}$.

FIGURE 7-13: BROWN-OUT PROTECTION CIRCUIT 2

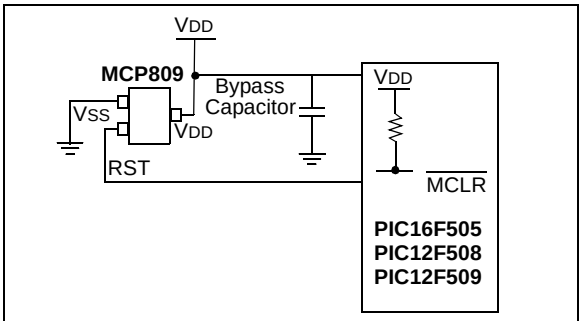


Note 1: This brown-out circuit is less expensive, although less accurate. Transistor Q1 turns off when V_{DD} is below a certain level such that:

$$V_{DD} \cdot \frac{R1}{R1 + R2} = 0.7V$$

2: Pin must be confirmed as $\overline{MCLR}$.

FIGURE 7-14: BROWN-OUT PROTECTION CIRCUIT 3



Note: This brown-out protection circuit employs Microchip Technology's MCP809 micro-controller supervisor. There are 7 different trip point selections to accommodate 5V to 3V systems.

IORWF	Inclusive OR W with f
Syntax:	[*label*] IORWF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(W).OR. (f) → (dest)
Status Affected:	Z
Description:	Inclusive OR the W register with register 'f'. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

MOVF	Move f
Syntax:	[*label*] MOVF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(f) → (dest)
Status Affected:	Z
Description:	The contents of register 'f' are moved to destination 'd'. If 'd' is '0', destination is the W register. If 'd' is '1', the destination is file register 'f'. 'd' = 1 is useful as a test of a file register, since status flag Z is affected.

MOVLW	Move Literal to W
Syntax:	[*label*] MOVLW k
Operands:	$0 \le k \le 255$
Operation:	k → (W)
Status Affected:	None
Description:	The eight-bit literal 'k' is loaded into the W register. The "don't cares" will assembled as '0's.

MOVWF	Move W to f
Syntax:	[*label*] MOVWF f
Operands:	$0 \le f \le 31$
Operation:	(W) → (f)
Status Affected:	None
Description:	Move data from the W register to register 'f'.

NOP	No Operation
Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Description:	No operation.

OPTION	Load OPTION Register
Syntax:	[*label*] OPTION
Operands:	None
Operation:	(W) → OPTION
Status Affected:	None
Description:	The content of the W register is loaded into the OPTION register.

10.2 DC Characteristics: PIC12F508/509/16F505 (Extended)

DC Characteristics			Standard Operating Conditions (unless otherwise specified) Operating Temperature -40°C ≤ TA ≤ +125°C (extended)				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ(1)**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**	2.0		5.5	V	See Figure 10-1
D002	VDR	**RAM Data Retention Voltage(2)**	—	1.5*	—	V	Device in Sleep mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	Vss	—	V	See **Section 7.4 "Power-on Reset (POR)"** for details
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See **Section 7.4 "Power-on Reset (POR)"** for details
D010	IDD	**Supply Current(3,4)**	— —	175 0.625	275 1.1	µA mA	FOSC = 4 MHz, VDD = 2.0V FOSC = 4 MHz, VDD = 5.0V
			— —	500 1.5	650 2.2	µA mA	FOSC = 10 MHz, VDD = 3.0V FOSC = 20 MHz, VDD = 5.0V (PIC16F515 only)
			— —	11 38	26 110	µA µA	FOSC = 32 kHz, VDD = 2.0V FOSC = 32 kHz, VDD = 5.0V
D020	IPD	**Power-down Current(5)**	— —	0.1 0.35	9.0 15.0	µA µA	VDD = 2.0V VDD = 5.0V
D022	IWDT	**WDT Current(5)**	— —	1.0 7.0	18 22	µA µA	VDD = 2.0V VDD = 5.0V

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

2: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

3: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

4: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VSS, T0CKI = VDD, $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

5: For standby current measurements, the conditions are the same as IDD, except that the device is in Sleep mode. If a module current is listed, the current is for that specific module enabled and the device in Sleep.

10.3 Timing Parameter Symbology and Load Conditions – PIC12F508/509/16F505

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS

T	
F Frequency	T Time

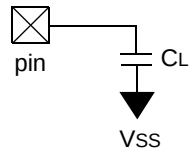
Lowercase subscripts (pp) and their meanings:

pp			
2	to	mc	$\overline{\text{MCLR}}$
ck	CLKOUT	osc	Oscillator
cy	Cycle time	os	OSC1
drt	Device Reset Timer	t0	T0CKI
io	I/O port	wdt	Watchdog Timer

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (high-impedance)	V	Valid
L	Low	Z	High-impedance

FIGURE 10-3: LOAD CONDITIONS – PIC12F508/509/16F505



Legend:

C_L = 50 pF for all pins except OSC2

15 pF for OSC2 in XT, HS or LP modes when external clock is used to drive OSC1

FIGURE 10-4: EXTERNAL CLOCK TIMING – PIC12F508/509/16F505

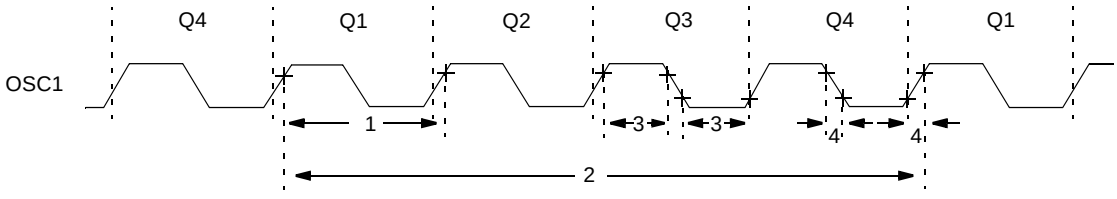


TABLE 10-6: RESET, WATCHDOG TIMER AND DEVICE RESET TIMER – PIC12F508/509/16F505

AC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended)				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ(1)**	**Max.**	**Units**	**Conditions**
30	TMCL	$\overline{\text{MCLR}}$ Pulse Width (low)	2000*	—	—	ns	VDD = 5.0V
31	TWDT	Watchdog Timer Time-out Period (no prescaler)	9* 9*	18* 18*	30* 40*	ms ms	VDD = 5.0V (Industrial) VDD = 5.0V (Extended)
32	TDRT	Device Reset Timer Period(2)	9* 9*	18* 18*	30* 40*	ms ms	VDD = 5.0V (Industrial) VDD = 5.0V (Extended)
34	TIOZ	I/O High-impedance from $\overline{\text{MCLR}}$ low	—	—	2000*	ns	

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 11-6: MAXIMUM WDT I_{PD} vs. V_{DD} OVER TEMPERATURE

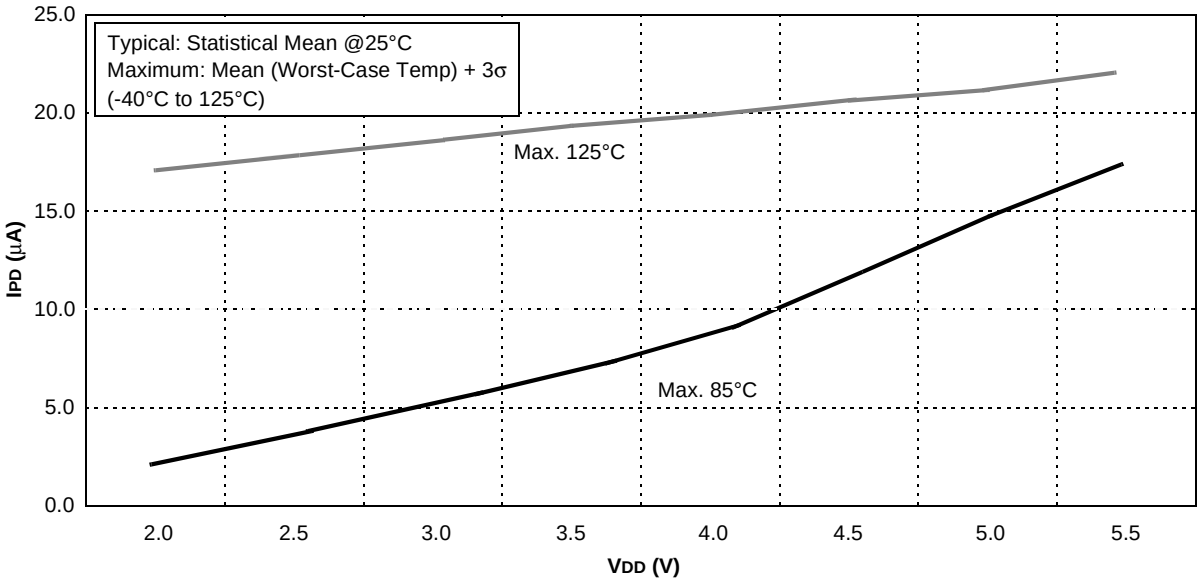
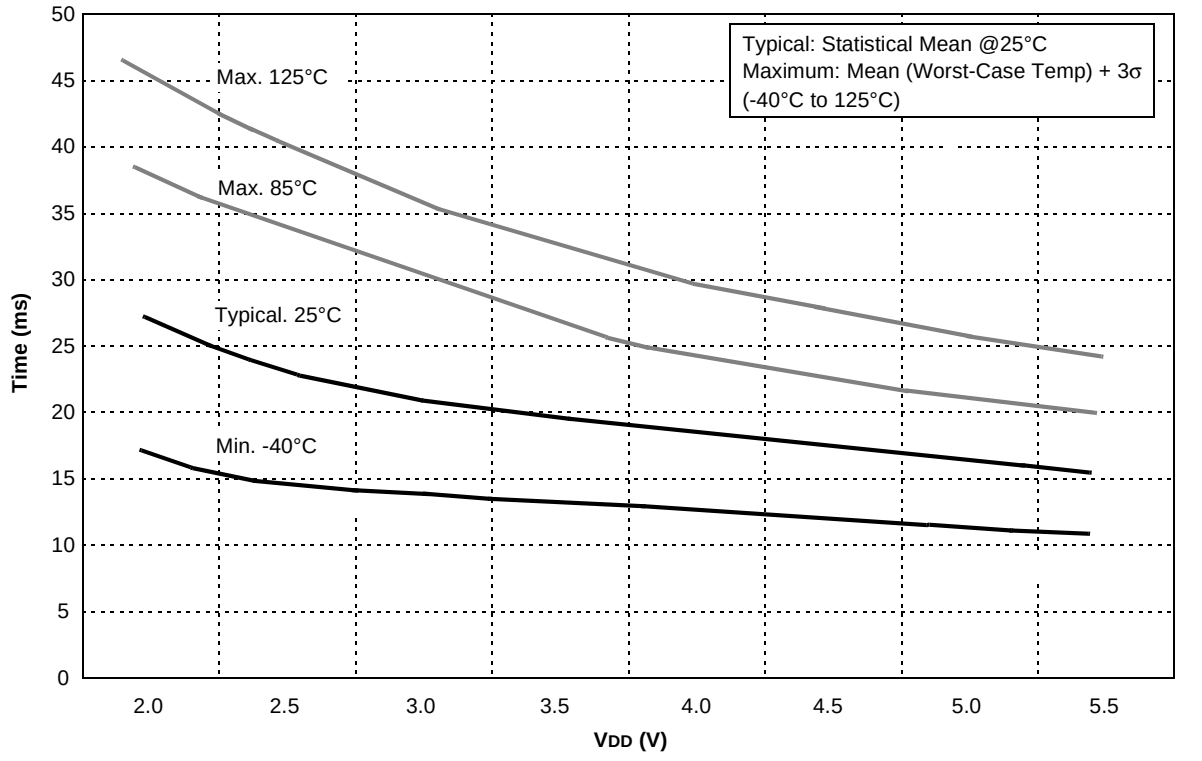


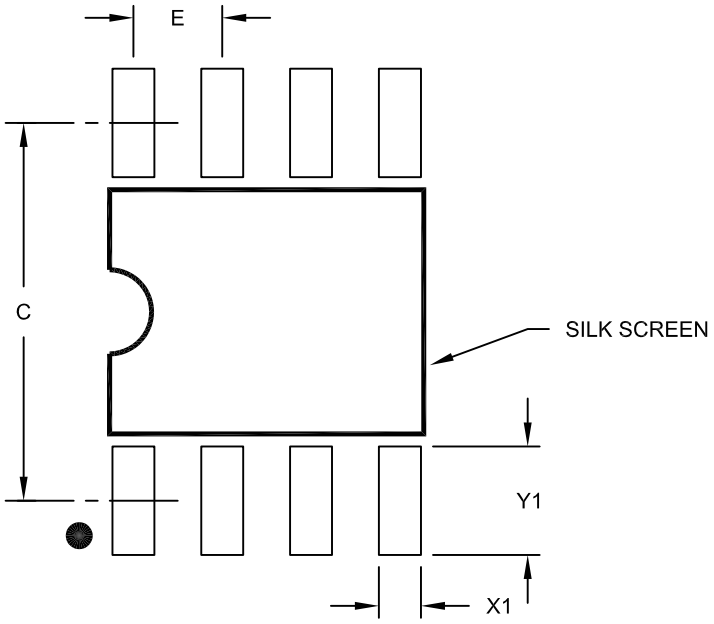
FIGURE 11-7: WDT TIME-OUT or DEVICE RESET TIMER vs. V_{DD} OVER TEMPERATURE (NO WDT PRESCALER)(1)



Note 1: Device Reset Timer (DRT) values are for case of Reset of power-up. Table 7-6 shows DRT values for the case of other types of Reset events.

8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

NOTES:

INDEX

READER RESPONSE

It is our intention to provide you with the best documentation possible to ensure successful use of your Microchip product. If you wish to provide your comments on organization, clarity, subject matter, and ways in which our documentation can better serve you, please FAX your comments to the Technical Publications Manager at (480) 792-4150.

Please list the following information, and use this outline to provide us with your comments about this document.

To: Technical Publications Manager Total Pages Sent _____

RE: Reader Response

From: Name _____

Company _____

Address _____

City / State / ZIP / Country _____

Telephone: (_____) _____ - _____ FAX: (_____) _____ - _____

Application (optional):

Would you like a reply? ___Y ___N

Device: PIC12F508/509/16F505 Literature Number: DS41236E

Questions:

1. What are the best features of this document?

2. How does this document meet your hardware and software development needs?

3. Do you find the organization of this document easy to follow? If not, why?

4. What additions to the document do you think would enhance the structure and subject?

5. What deletions from the document could be made without affecting the overall usefulness?

6. Is there any incorrect or misleading information (what and where)?

7. How would you improve this document?